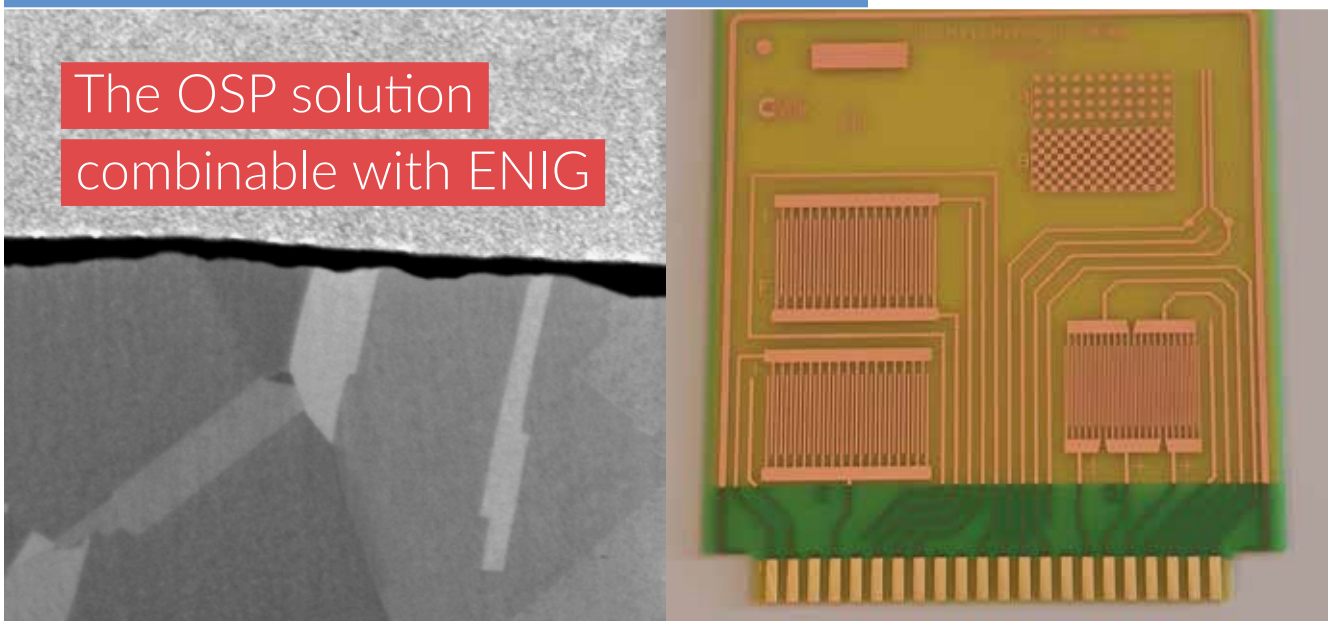
# OS-Tech® SIT 2




## Development by design

Organic surface finishes provide a solderable environmentally friendly finish for fabricators in the electronics industry. Key to the potency of the process is the amount of reflow cycles the finish can endure. Additionally, the thickness of the coating is a key quality indicator or process control tool as it is a measure of potential for solder joint quality implications.

Like the sister process OS-Tech® the new OS-Tech® SIT 2 can guarantee multiple solder reflow cycles and is applicable to work in combination with Atotech's production proven ENIG processes.

## Features and benefits

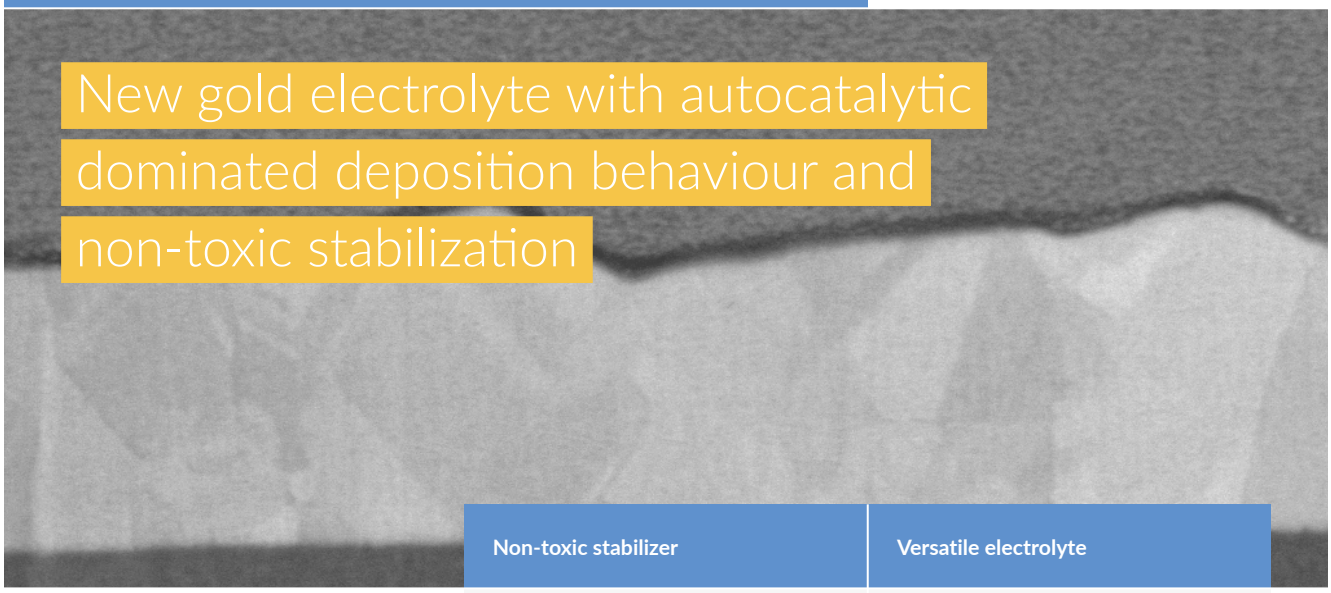
- Drop in for existing lines
- Application of Atotech equipment possible
- Short processing times
- Heat resistant coating applicable for soldering and press fit applications

**OS-Tech® SIT 2 process flow**

- Acid Cleaner
- MicroEtch
- OS-Tech Pre-Dip
- OS-Tech® SIT 2
- Dryer

# Aurotech® G-Bond 3

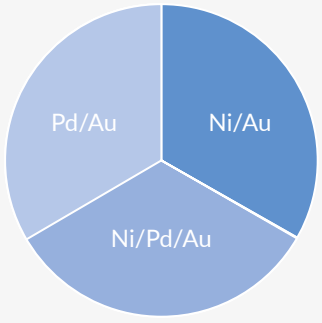
mks Atotech



## New gold electrolyte with autocatalytic dominated deposition behaviour and non-toxic stabilization

**Non-toxic stabilizer**

**Versatile electrolyte**




**0.6**

g/l gold content in plating solution

**10**

MTO bath lifetime

### Latest generation corrosion-free gold for ENIG, ENEPIG, and EPAG

Aurotech® G-Bond 3 is the latest generation gold electrolyte that fulfills all industry standards for ENIG, ENEPIG, and EPAG plating. It exhibits autocatalytic dominated plating properties to mitigate the attack to the underlying layer and enables the plating of high gold thickness where required. Besides offering the highest bath stability and excellent layer performance, the process exhibits the benefit of non-toxic stabilization so that no handling of KCN replenishment is required. The new process combines the known benefits of Aurotech® G-Bond 2 with outstanding stability, long bath life, and a new and toxic-free stabilizer.

### Features and benefits

- Non-toxic stabilizer, no KCN handling required for replenishment
- Low Au-content (0.6 g/l)
- High bath stability, no plate out
- Long bath life (10 MTO)
- >95% ENIG corrosion level 0
- Excellent thickness distribution of < 5% COV

# Stannatech® 2000 H

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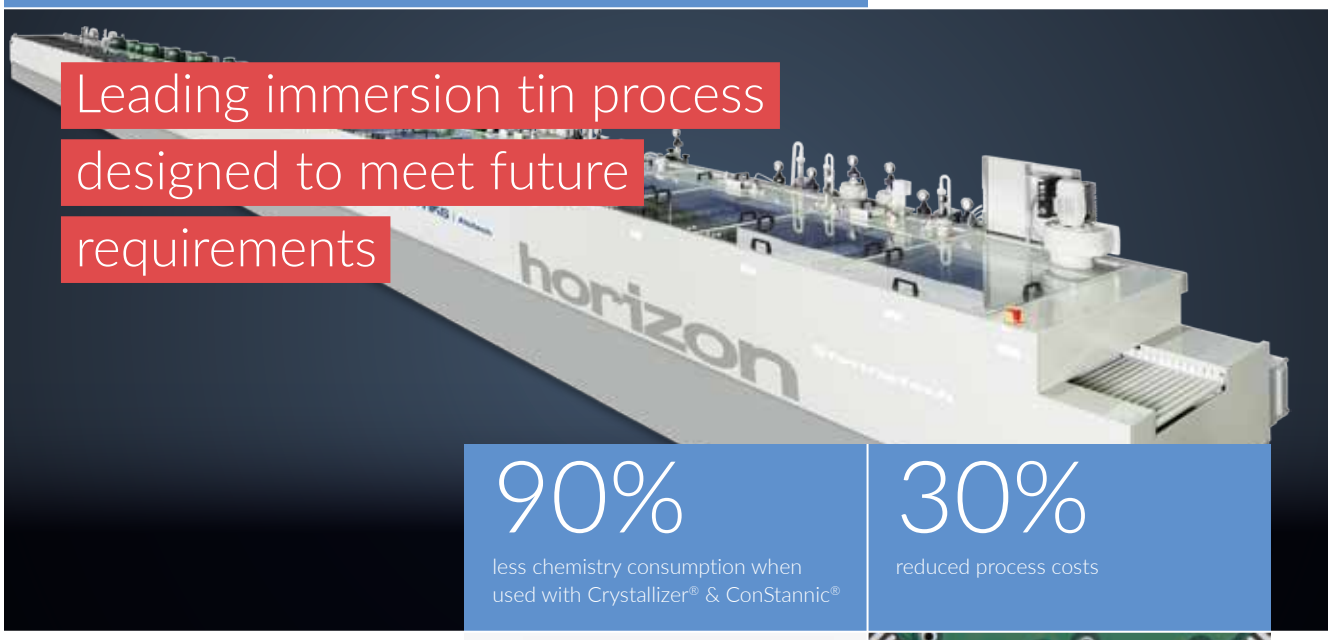
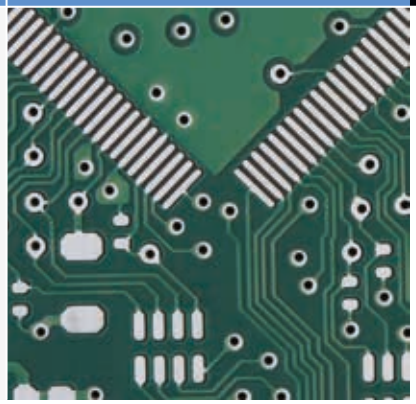



## Leading immersion tin process designed to meet future requirements

**90%**
less chemistry consumption when used with Crystallizer® & ConStannic®

**30%**
reduced process costs



- Cleaner
- MicroEtch
- Conditioner
- Tin bath
- Special rinse
- Ionic contamination reduction (optional)
- Advanced surface protection

## Excellent whisker control for highest reliability

MKS' Atotech offers chemistry, equipment and auxiliaries out of one hand, thereby providing superior quality and cost-efficiency while saving chemistry. Our Stannatech® 2000 H chemstry is best used together with our Horizon® Stannatech plating line. Horizon® Stannatech is fully automated and ideally suited for the automotive industry.

Especially HDI, automotive, and package substrate customers worldwide trust in the exceptional solder joint integrity and corrosion resistance of our chemistry in combination with our equipment. Using Stannatech® 2000 H together with Horizon® Stannatech can reduce costs by up to 30%, while water, energy, and chemistry consumption can be lowered by up to 90%.

## Features and benefits

- Low operating temperatures reduce thermal stress on the board causing lower warpage compared to HASL process
- Excellent bath stability
- Unique multiple soldering performance provides higher yield and flexible production
- Low ionic contamination values
- 12 months lifetime of the chemistry